

## SMAF Plastic-Encapsulate Diodes

### SS56LF Schottky Rectifier Diode

#### Features

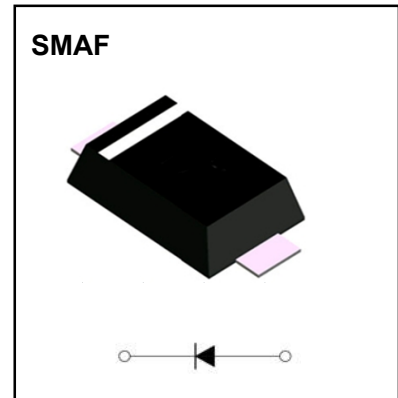
- $I_{F(AV)}$  5A
- $V_{RRM}$  60V
- High surge current capability
- Polarity: Color band denotes cathode
- Low peak forward voltage

#### Applications

- Rectifier

#### Marking

- SS56LF:SS56L



#### Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	SS56LF
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		60
Maximum RMS Voltage	$V_{RMS}$	V		42
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load	5.0
Surge(Non-repetitive)Forward Current	$I_{FSM}$	A	60Hz Half-sine wave, 1 cycle, $T_a=25\text{ C}$	120
Junction Temperature	$T_J$	$^{\circ}\text{C}$		-55 ~ +150
Storage Temperature	$T_{STG}$	$^{\circ}\text{C}$		-55 ~ +150

#### Electrical Characteristics (T=25 $^{\circ}\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		SS56LF	
Peak Forward Voltage	$V_F$	V	$I_F=5.0\text{A}$	$T_a=25^{\circ}\text{C}$	0.46(TYP)	0.50(MAX)
Peak Reverse Current	$I_{RRM1}$	mA	$V_{RM}=V_{RRM}$	$T_a=25^{\circ}\text{C}$	0.05(TYP)	0.3(MAX)
	$I_{RRM2}$			$T_a=125^{\circ}\text{C}$	20	
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^{\circ}\text{C}/\text{W}$	Between junction and ambient		112	
	$R_{\theta J-L}$		Between junction and lead		12	
Juction Capacitance (Typical)	$C_j$	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C		400	

#### Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on FR4 PCB double sided copper mini pad

# Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

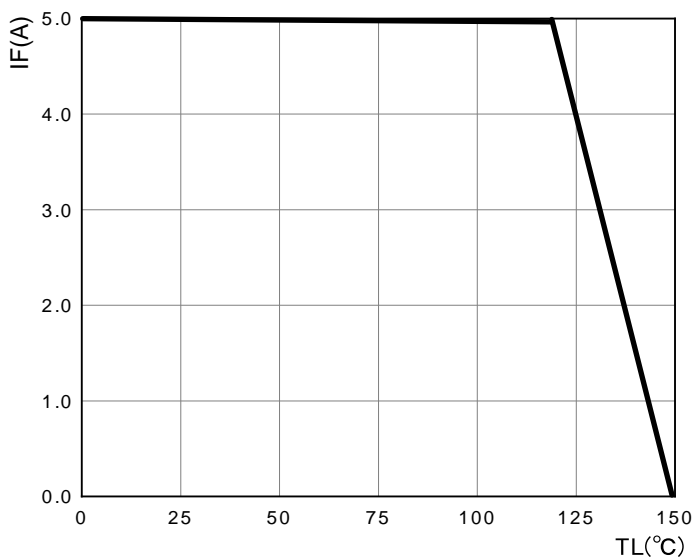


FIG 2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

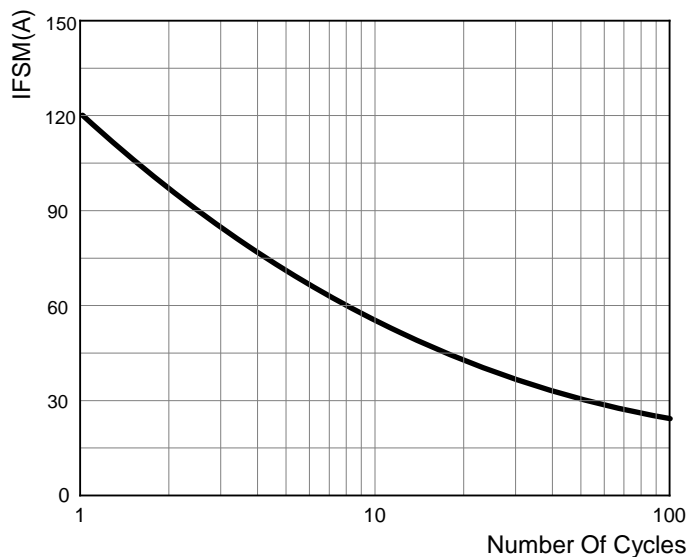


FIG.3: TYPICAL FORWARD CHARACTERISTICS

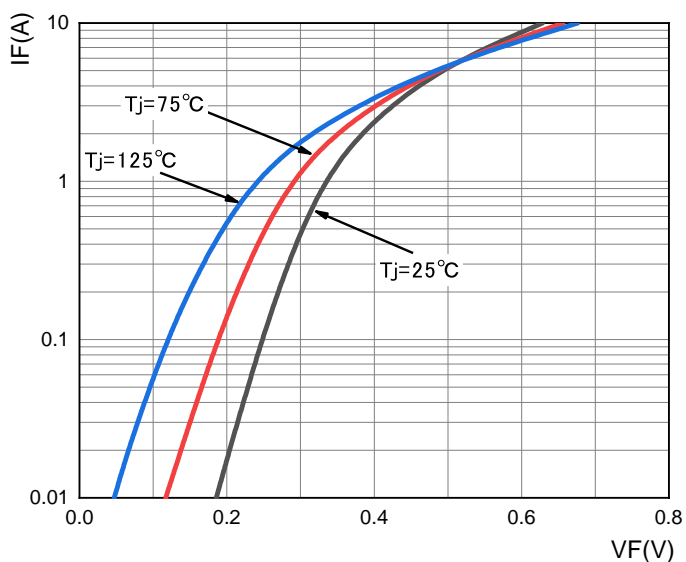
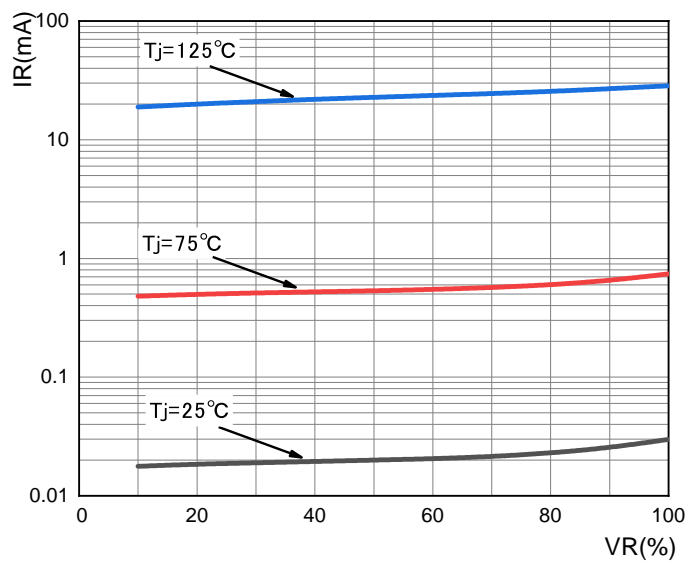
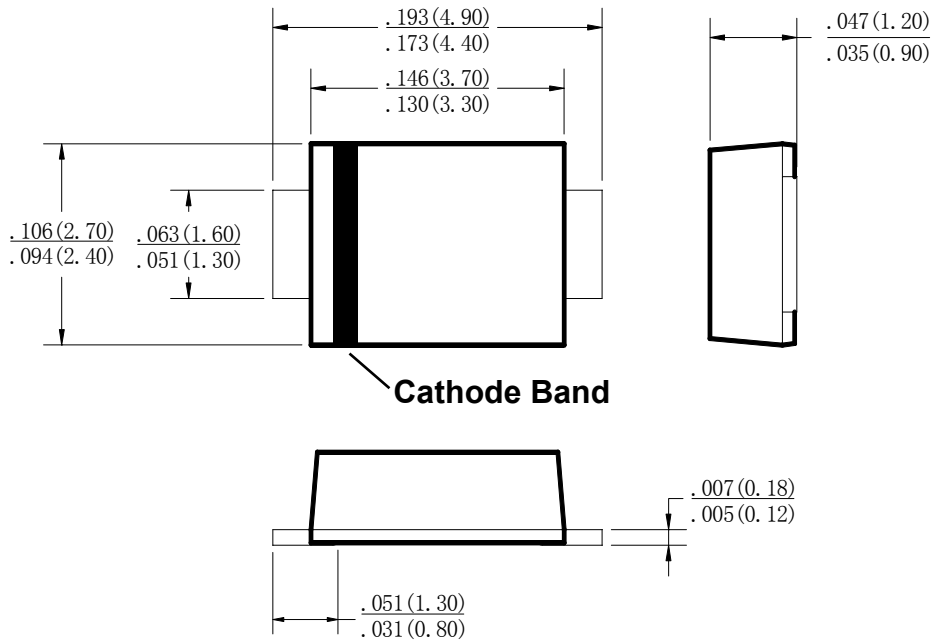


FIG.4: TYPICAL REVERSE CHARACTERISTICS

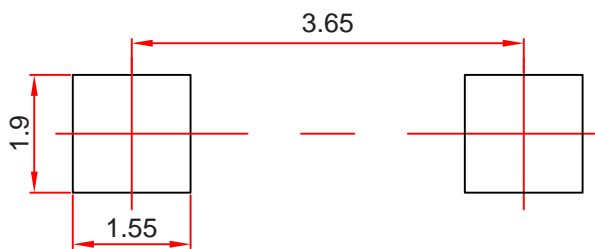


## SMAF Package Outline Dimensions



Dimensions in inches and (millimeters)

## SMAF Suggested Pad Layout



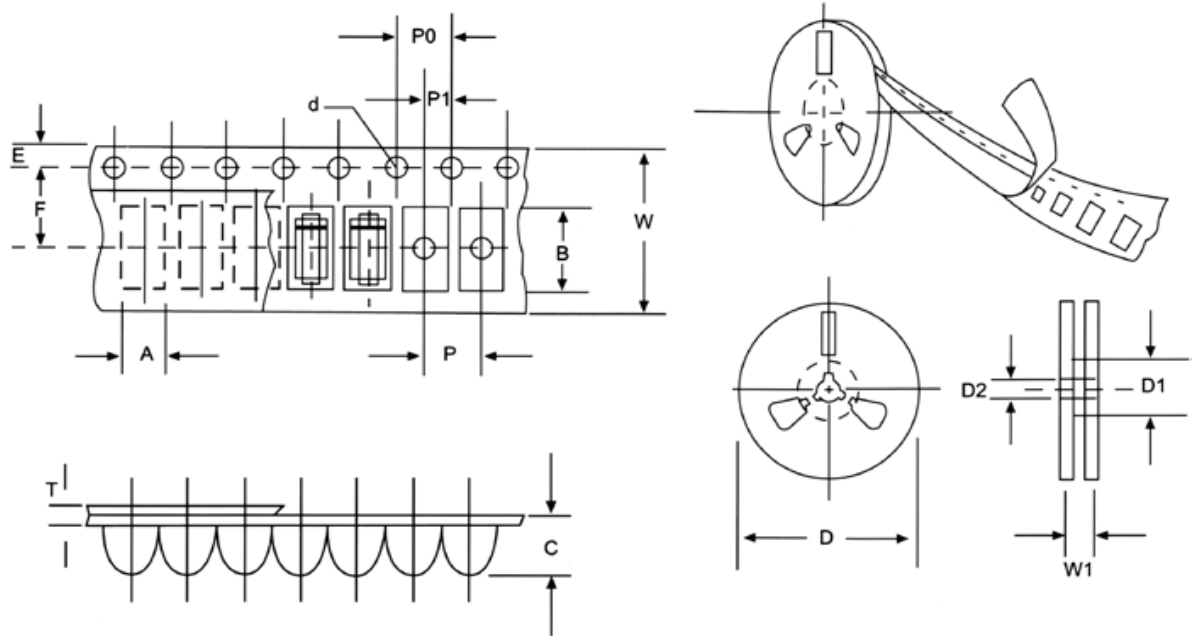
### Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$ mm.
3. The pad layout is for reference purposes only.

### NOTICE

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# Reel Taping Specifications For Surface Mount Devices-SMAF



**FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING**

ITEM	SYMBOL	SMAF mm(inch)
Carrier width	A	2.83±0.1(0.112±0.004)
Carrier length	B	4.90±0.1(0.193±0.004)
Carrier depth	C	1.45±0.1(0.057±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	178±2.0(7.0±0.079)
Reel inner diameter	D1	54±1.0(2.13±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.23-0.29(0.009-0.011)
Tape width	W	12.0±0.1(0.472±0.004)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.